100% Material Declaration Data Sheet CP56

Average Weight: 0.1 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.00215**	**2.15%**
	Silicon	7440-21-3	100.00		0.00215	
Die Attach Material					**0.0005**	**0.50%**
	Silver	7440-22-4	78.00		0.00039	
	Resin	Trade Secret	22.00		0.00011	
Encapsulant					**0.03956**	**39.56%**
	Epoxy Resin	Trade Secret	6.00		0.0023736	
	Phenolic Resin	Trade Secret	6.00		0.0023736	
	Carbon Black	1333-86-4	0.50			
	Bismuth	7440-69-9	Max 1.00		0.0003956	
	SiO2 Filler	60676-86-0	86.50		0.0342194	
Laminate					**0.0126**	**12.60%**
	Bismaleimide / Triazine Board	13676-54-5 / 25722-66-1	72.285		0.00910791	
	Copper	7440-50-8	9.780	Metal Layer	0.00123228	
	Nickel	7440-02-0	7.890	Metal Layer	0.00099414	
	Gold	7440-57-5	1.140	Metal Layer	0.00014364	
	Antimony Pentoxide	1314-60-9	0.005	Flame Retardant	0.00000063	
	Brominated Resin	68541-56-0	8.90	Flame Retardant	0.0011214	
Bond Wire					**0.00023**	**0.23%**
	Gold	7440-57-5	100.00		0.00023	
Solder Balls					**0.04496**	**44.96%**
	Tin	7440-31-5	63.00		0.0283248	
	Lead	7439-92-1	37.00		0.0166352	

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Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
4/06/06	1.0	Initial release.
7/21/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.